

60227 IEC 52(RVV)型 聚氯乙烯二次挤压护套软线
 60227 IEC 53(RVV)型 聚氯乙烯二次挤压护套软线
 60227 IEC 52(RVV) PVC-sheathed (dual extrusion) flexible cord
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软电线电缆系列

FLEXIBLE WIRES & CABLES

3C证书号:
2005010105158879



应用范围

适用于家用电器、仪器仪表、电子设备、动力设备和其它一般移动场合各部件的连接，为加强型。

APPLICATIONS

For movable wiring of household appliances, instruments/ gauges, electronic equipment, power units. enhanced model.

电线结构

多股细裸束绞铜丝或镀锡铜丝导体；
PVC/D型绝缘,填充型PVC内护套，PVC/ST5型护套。

WIRE MAKE-UP

Fine bare copper/tinned copper stranded conductor;
PVC/D insulation, infill PVC undersheath, PVC/ST5 sheath

技术参数

- ① 温度范围：固定安装-15℃ ~ +70℃
移动安装-5℃ ~ +70℃
- ② 额定电压：U₀/U52(RVV)300/300V
53(RVV)300/500V
- ③ 符合标准：GB/T5023.5-2008
- ④ 导体标准：GB/T3956-1997第5种
- ⑤ 弯曲半径：大于4×电线外径(固定)
大于15×电线外径(一般移动)

TECHNICAL DATA

- ① Operating Temp.:
-15℃ ~ +70℃ for fixed wiring
-5℃ ~ +70℃ for movable wiring
- ② Rated Voltage: U₀/U52(RVV)300/300V; 53(RVV)300/500V
- ③ Governing Standards: GB/T5023.5-2008
- ④ Conductor Standards: Category 5 in GB/T 3956-1997
- ⑤ Bending Radius:
more than 4 × wire O.D. (fixed wiring)
more than 15 × wire O.D. (normal movable wiring)

导体截面 Cross Section 芯数 × mm ² Core. No. × mm ²	导体结构 Conductor Structure 芯数 × 根数/单根直径 Core. No. × Cond. No./O.D	标称外径 Nominal O.D. mm	最大外径 Max O.D. mm	重量(近似) Approx. Weight Kg/Km	导体20℃时 最大电阻 Max. Cond. R@20℃ ≤ (Ω/Km)	环境温度 30℃架空时 参考载流量(A) Ambient (aerial cable)
60227 IEC 52 (RVV) 300/300V						
2×0.5	2×16/0.20	5.56	5.9	46.1	39.0	9
2×0.75	2×24/0.20	6.08	6.3	57.1	26.0	11
3×0.5	3×16/0.20	5.86	6.3	54.8	39.0	7
3×0.75	3×24/0.20	6.42	6.7	68.9	26.0	8
60227 IEC 53 (RVV) 300/500V						
2×0.75	2×24/0.20	7.12	7.2	74.9	26.0	11
2×1	2×32/0.20	7.40	7.5	84.2	19.5	13
2×1.5	2×30/0.25	8.32	8.6	110	13.3	17
2×2.5	2×50/0.25	10.14	10.6	163	7.98	24
3×0.75	3×24/0.20	7.49	7.6	86.5	26	8
3×1	3×32/0.20	7.80	8.0	99.7	19.5	10
3×1.5	3×30/0.25	8.99	9.4	129	13.3	11
3×2.5	3×50/0.25	10.92	11.4	201	7.98	18

▲ 载流量是周围温度设定在30℃时的计算值。电线芯数、周围温度、布线状况等条件改变时应乘以系数。(见附录)

▲ Current-carrying capacity is the calculated value based on a ambient temperature of 30℃ and is to be multiplied by a factor when application conditions including number of cores, ambient temperature and wiring condition are changed. (see Appendix)